Sensors

Getting Ready for the production of EC Strip Sensors

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The numbers

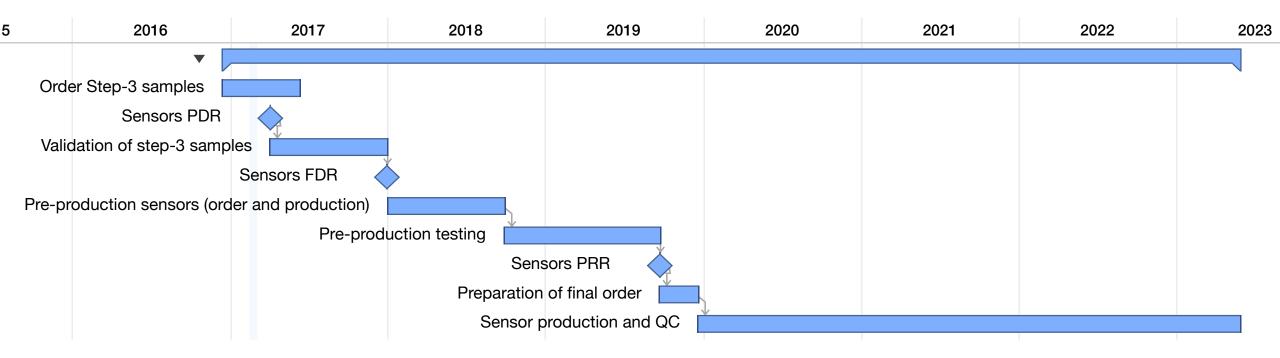
Assuming a 20% contingency, rough numbers are

| | R0 | R1 | R2 | R3 | R4 | R5 | Total |
|--------------------|------|------|------|------|------|------|-------|
| Number of sensors | 1000 | 1000 | 1000 | 2000 | 2000 | 2000 | 9000 |
| Number of rows | 4 | 4 | 2 | 4 | 2 | 2 | |
| Channel per sensor | 4360 | 5640 | 3076 | 3592 | 2052 | 2308 | |

9000 sensors to receive and test to different levels of detail.

Preproduction is a 5% of the total: 450 sensors

The schedule



Validation of MS-3 sensors during this year (barrel)
Final Design Review by end of this year. Preproduction starts.
One year to validate and have the Production Readiness Review

The work

- 1. Design of all 6 sensor types (more or less done)
- 2. Getting ready to validate preproduction.
 - a. What? Which tests, equipment needed? Irradiations?
 - b. Who?
 - c. How different shapes are distributed?
 - ✓ One shape at least 2 sites?

2.1. Specifications of ITk production testing

Tests to be performed on every sensor:

| Action | Equipment needed | Quality Control Spec. |
|---|--|--|
| Storage of Components | Storage Cabinets with dry atmosphere | |
| Visual Inspection: Check for scratches, blemishes, trace continuity, sensor edge roughness, bias rail and guard ring | Optical Microscope (with automated inspection software), | No chips, cracks or no other irregularities clean sensor |
| Sensor bow | Non-contact Coordinate Measurement Machine SCC | Total bow < 200μm |
| IV 0700 V with 10V/10s | Probe station with N2/RH control, SCC or Dry atm. | I < 0.1μm/cm ² @ 700V, @ Room Temperature No onset of micro-discharge up to 700V |
| CV 0700V with 10V/5s | As above | Full Depletion Voltage < 330V |

Definitions:

- Standard Cleanroom Conditions (SCC): ISO 7 (class 10000), Temperature = $19\pm1^{\circ}$ C, Relative Humidity = $40\pm10\%$
- Dry atmosphere: Relative Humidity < 5% at 21°C dry air or nitrogen

2.1. Specifications of ITk production testing

Tests to be performed on a subset of sensors (10% - 1% of total), all done at SCC:

| ActionData | Equipment needed | Quality Control Spec. |
|--|---|---|
| Full Strip tests R_{bias}, C_{coupling}, I_{leakage} on every strip | Automatic Probe Station (multi-channel probe card, switching matrix,) | Number of strips with problem (pinhole, shorts, opens, implant breaks) <2% |
| Current stability test at Vbias=-700 V | Probe-station or a test box Dry atm., 20°C | Current variation less then 15% in 24Hours |
| Additional testsCint,Rint,PTP,Top metal resistance | Probe station | 1 pF/cm at 300V at 100 kHz G Ω range at 600V (nonirrad.) < 15 Ω /cm |
| DatabaseSensor is registered, data uploaded to database | PC + internet | |

2.1 EC Sensor testing rate

- Time estimation prepared for a site with 1 probe station
- All tests are equivalent for barrel and EC sensors except the full strip tests that will be very probably more complicated for EC sensors
- 100% of sensors
 - Visual inspection,
 - Metrology
 - IV,CV
 - Sensor registration in database
 - 1:40 hours/sensor → 4 sensors/day
- Subset of sensors starts at 10% and reduced to 1% of total
 - Full strip tests: ≈ 14 hours/sensor single needle strip—by—strip (overnight running possible)
 - ≈ 5 hours/sensor with EC specific multi-channel probe card (including alignments for every individual segments)
 - PTP, Cint, Rint
 - Current stability (24h running in a test box, multiple sensors at time, parallel measurement)
 - Sensor registration in database
 - 1 sensor/day
- **e.g. one site** $\approx 1000 \text{ sensors} \Rightarrow 250 + 100 = 350 \text{ days}$

2.2 Number of sites involved in ITk EC sensor testing

Table 13.2: Intended Number of Production Build Sites for the ITk Strip Detector

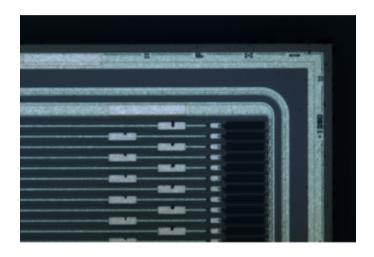
| Item | Sites |
|---------------------------------|-------|
| Sensor Testing | 4 |
| ABCStar Wafer Probing | 2 |
| HCCStar Wafer Probing | 2 |
| Power Board Assembly | 2 |
| Barrel Hybrid Assembly | 2 |
| End-cap Hybrid Assembly | 2 |
| Barrel Module Assembly | 8 |
| End-cap Module Assembly | 7 |
| EoS Card Assembly | 2 |
| Barrel Bus Tape Testing | 2 |
| End-cap Bus Tape Testing | 2 |
| Barrel Core Production | 2 |
| End-cap Core Production | 2 |
| Barrel Module on Core Assembly | 2 |
| End-cap Module on Core Assembly | 2 |

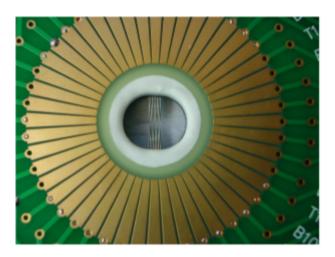
9000 EC sensors to be tested, only 2 EC sensor testing sites is insufficient

Q: how many sites will be included in production testing of EC sensors / number of EC sensors per site?

Full strip tests – barrel sensor

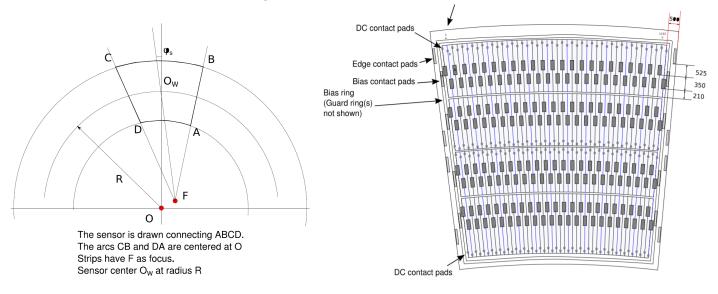
- R_{bias}, C_{coupling}, I_{leakage} on each sensor strip
- for barrel sensors the testing contact pads are in line
- measurement set-up with a custom 32 channel low-leakage probe card with associated switching and multiplexing equipment developed at Cambridge Uni.
- Time required for one sensor full strip test reduced from 14 hours with single needle to less than 3 hours.





Full strip tests – EC sensors specific

- 6 different EC sensor designs
- wedge shaped strips with a stereo angle implemented in the sensors
- 2 or 4 columns of strips on a sensor
- contact pads positioned on circular arch
- the angular pitch is constant for given segment but may be different among segments of one sensor
- Different absolute pitch of contact pads
- Number of strips in columns may differ (e.g. R0: Column 1 and 2 : 1024 strips , Column 3 and 4 1152 strips)
- -> up to 4 different multi-channel probe-cards needed for one sensor



Full strip tests of EC sensors are not straightforward – single-needle vs multi-channel probe cards

The nearer Future: ROs

| Group | 1st Delivery | 2nd Delivery | 3rd Delivery | All | |
|------------------|--------------|--------------|--------------|-----|----------|
| Melbourne | - | - | 5 | 5 | |
| Toronto/Carleton | 5 | 3 | 12 | 20 | |
| Vancouver | _ | 8 | 12 | 20 | |
| Charles U. | _ | 1 | 2 | 3 | |
| IoP AS CR. | 5 | _ | - | 5 | (2 belor |
| Freiburg | 5 | 3 | 6 | 14 | |
| Dortmund | 1 | 4 | 8 | 13 | |
| Berlin | 1 | 3 | 5 | 9 | |
| DESY | 8 | 7 | 13 | 28 | |
| NIKHEF | _ | 2 | 4 | 6 | |
| IFIC | 5 | 4 | 6 | 15 | |
| Uppsala | - | 5 | 10 | 15 | |
| Ljubljana | 2 | - | - | 2 | |
| | | | | | |
| Total | 32 | 40 | 83 | 155 | |

The nearer future: RO

- Need to start an irradiation campaign
 - Miniatures:
 - some already irradiated or being irradiated at CYRIC
 - Might want to irradiate with neutrons
 - Large sensors: at CERN?
- Need to characterize fast the first 2 batches so that the third one is delivered soon.
 - A bit of reshuffling of distribution queue so that testing centers receive first.